

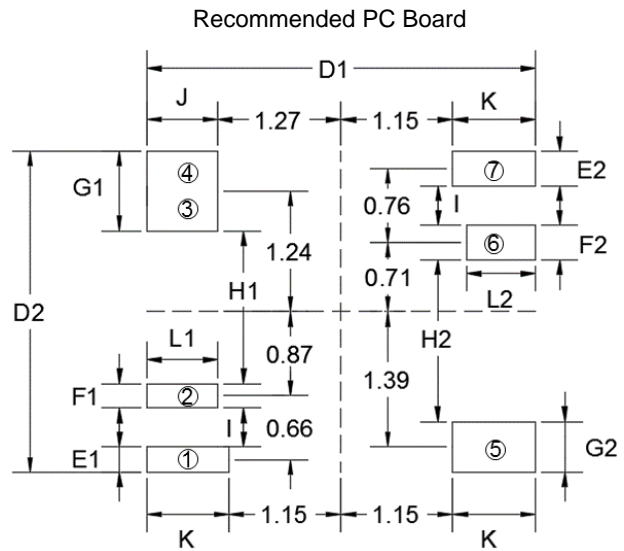
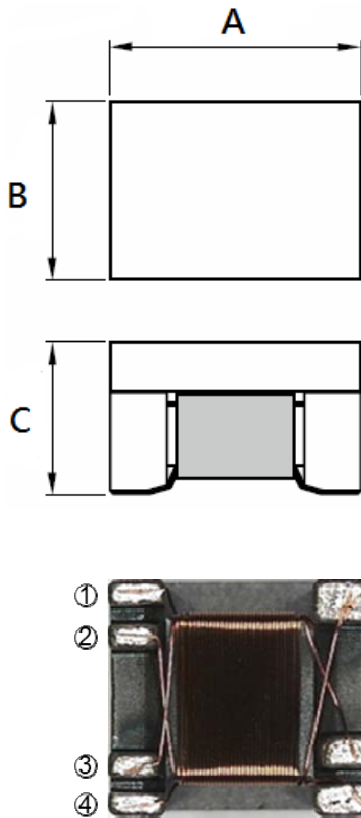
1. Part No. Expression:

SLT353229201N4A

(a) (b) (c) (d) (e)

- a) Series Code
- b) Dimension Code
- c) Inductance Code
- d) Material Code
- e) Internal Controlled Code

2. Configuration & Dimensions:



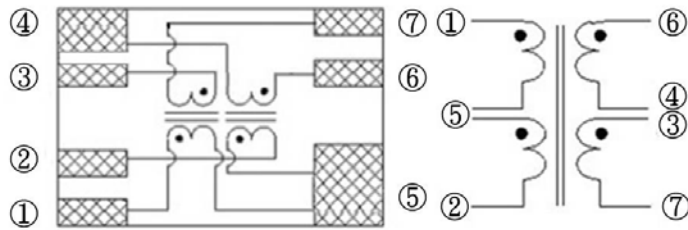
PC board should be designed so that products can prevent damage from mechanical stress when warping the board. Products shall be positioned in the sideways direction against the mechanical stress to prevent failure.

Unit: mm

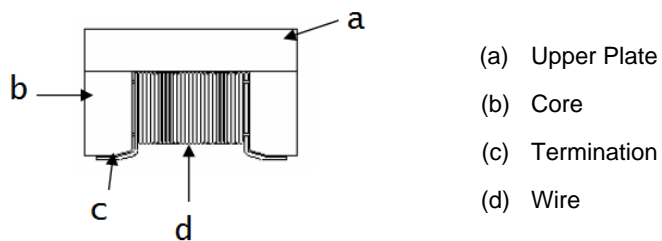
A(mm)	B(mm)	C(mm)	D1(mm)	E1(mm)	F1(mm)	G1(mm)	H1(mm)	I(mm)
3.50±0.2	3.20±0.2	2.90 Max	4.00 Ref.	0.26 Ref.	0.25 Ref.	0.82 Ref.	1.57 Ref.	0.40 Ref.
J(mm)	K(mm)	L1(mm)	D2(mm)	E2(mm)	F2(mm)	G2(mm)	H2(mm)	L2(mm)
0.73 Ref.	0.85 Ref.	0.73 Ref.	0.33 Ref.	0.36 Ref.	0.36 Ref.	0.52 Ref.	1.66 Ref.	0.71 Ref.

NOTE: Specifications subject to change without notice. Please check our website for latest information.

3. Schematic:



4. Material List:



5. General Specification:

- (a) Operating Temp.: -40°C to +85°C (including self - temperature rise)
- (b) Storage Temp.: -40°C to +85°C (on board)
- (c) Humidity Range: 85 ± 2% RH
- (d) Storage condition (component in its packaging)
 - i) Temperature: Less than 40°C
 - ii) Humidity: 60% RH

NOTE: Specifications subject to change without notice. Please check our website for latest information.

6. Electrical Characteristics:

Part Number	Inductance (uH Min.) (DC bias 0mA) ① to ② or ③-④ short ⑥ to ⑦	Test Frequency (Hz)	Insertion loss (dB Max.) 1-100MHz	Cp Capacitance (pF Max.) ③ to ⑥	Turns ratio ① to ②:④-⑤
SLT353229201N4A	200	0.1V/100K	-1.0	35	1:1

7. Soldering:

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-1 Solder Re-flow

Recommended temperature profiles for re-flow soldering in Figure 1.

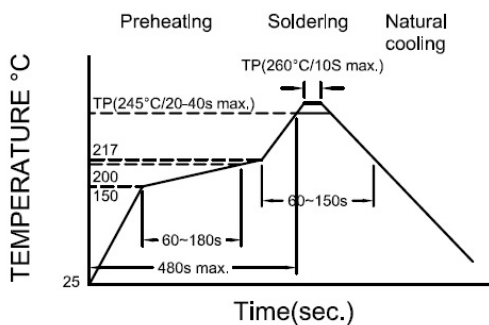
7-2 Soldering Iron (Figure 2)

Products attachment with soldering iron is discouraged due to the inherent process control limitations.

In the event that a soldering iron must be employed the following precautions are recommended.

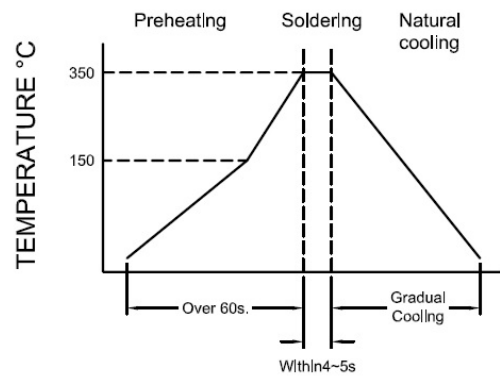
Note :

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) 1.0mm tip diameter (Max.)
- d) Use a 20 watt soldering iron with tip diameter of 1.0mm
- e) Limit soldering time to 4~5 secs.



Reflow times: 3 times max

Fig.1



Iron Soldering times: 1 times max

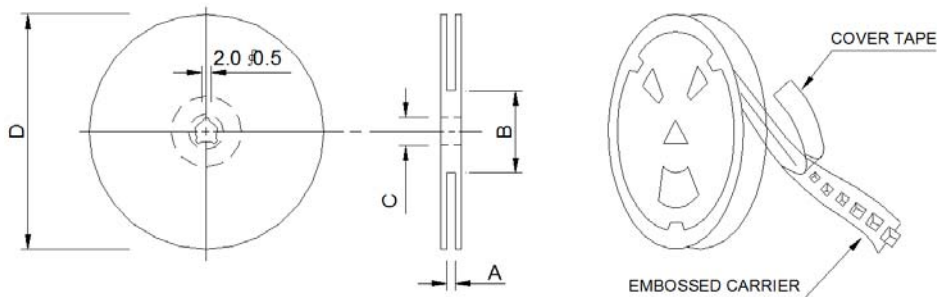
Fig.2

NOTE: Specifications subject to change without notice. Please check our website for latest information.



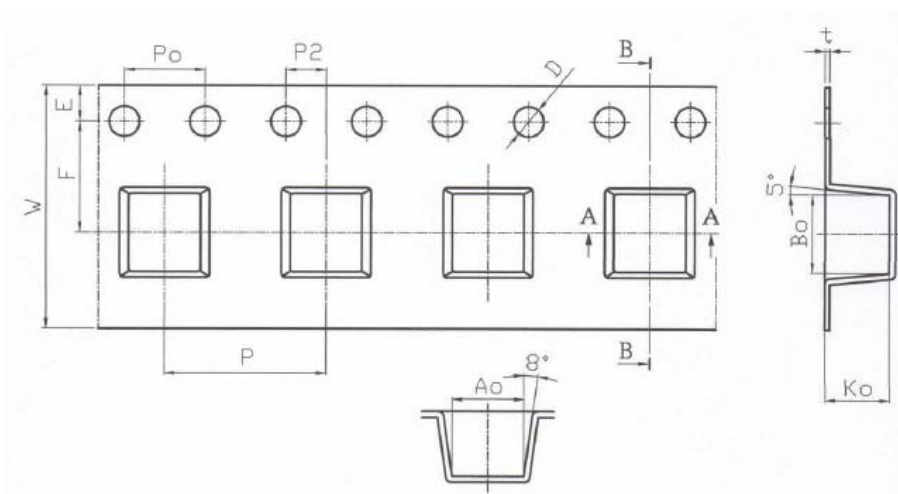
8. Packaging Information:

8-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x12	12.5±0.5	100±2.0	13.5±0.5	330

8-2 Tape Dimension

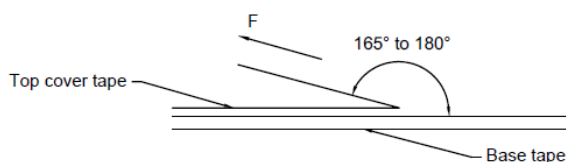


Series	P(mm)	Po(mm)	P2(mm)	Bo(mm)	Ao(mm)	Ko(mm)
	8.00±0.10	4.00±0.10	2.00±0.05	3.90±0.10	3.55±0.10	3.20±0.10
SLT353229	D(mm)	E(mm)	F(mm)	W(mm)	t(mm)	
	1.05+0.10/-0	1.75±0.10	5.50±0.05	12.00±0.10	0.30±0.05	

NOTE: Specifications subject to change without notice. Please check our website for latest information.

8-3 Packaging Quantity

SLT	353229
Chip / Reel	2000
Inner Box	4000
Carton	32000

8-4 Tearing Off Force

The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- Recommended products should be used within 12 months from the time of delivery.
- The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Vacuum pick up is strongly recommended for individual components.
- Bulk handling should ensure that abrasion and mechanical shock are minimized.

NOTE: Specifications subject to change without notice. Please check our website for latest information.